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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kumar et al.  
Serial No.: 09/903,114  
Filed: July 11, 2001  
For: THERMAL PROCESSING  
SYSTEM AND METHODS FOR  
FORMING LOW-K DIELECTRIC  
FILMS SUITABLE FOR  
INCORPORATION INTO  
MICROELECTRONIC DEVICES

Examiner: Unknown  
Group Art Unit: Unknown  
Docket No.: FSI0006/US/2

Commissioner for Patents  
Washington, DC 20231

I CERTIFY THAT ON Dec 7, 2001, THIS PAPER IS  
BEING DEPOSITED WITH THE U.S. POSTAL SERVICE AS FIRST  
CLASS MAIL IN AN ENVELOPE ADDRESSED TO THE  
COMMISSIONER FOR PATENTS, WASHINGTON, DC 20231

Paula J. Breeden

INFORMATION DISCLOSURE STATEMENT

The documents listed on the enclosed Form PTO-1449 are presented pursuant to  
Applicant's duty of disclosure under 37 C.F.R. 1.56. A copy of each of these documents is  
enclosed.

No fee is believed to be necessary for the consideration of this Information  
Disclosure Statement since it is being filed before the receipt of an Office Action on the merits. In  
case the papers cross in the mail, it is requested that consideration of this Information Disclosure  
Statement be given under 37 C.F.R. § 1.97 (c)(2). If any fee is required, please charge our Deposit  
Account No. 50-1775 and notify us of the same.

Respectfully Submitted,

Dated: December 7, 2001

By:

David B. Kagan  
David B. Kagan, Reg. No. 38,406  
KAGAN BINDER, PLLC  
Suite 200 Maple Island Building  
221 Main Street North  
Stillwater, Minnesota 55082  
651-275-9804 X 107